BGF128 HDMI Interface ESD Protection

RF & Protection Devices



Edition 2009-04-01

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Previous Version: 2009-03-02, V2.0						
Page	Subjects (major changes since last revision)					
4	Marking updated					
6	Figure 3 added					



BGF128

Features

- · ESD protection circuit for control data lines of an HDMI interface
- ESD protection according to IEC61000-4-2 for ± 15 kV contact discharge on external IOs
- Wafer level package with SnAgCu solder balls
- 400 μm solder ball pitch
- RoHS and WEEE compliant package



WLP-8-9-N-3D



Description

BGF128 is an ESD protection circuit for control data lines of an HDMI interface. All external IOs are protected against ESD pulses of \pm 15 kV contact discharge according to IEC61000-4-2. The wafer level package is a green lead-free and halogen-free package with a size of only 1.15 mm x 1.15 mm and a total height of 0.6 mm.

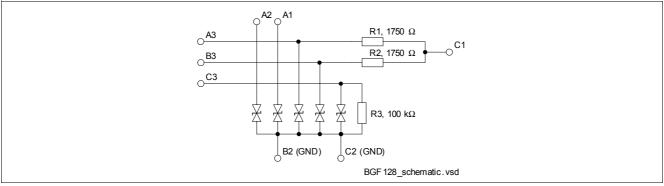


Figure 1 Schematic

Туре	Package	Marking	Chip
BGF128	WLP-8-9	28	N0747

Table 1Maximum Ratings

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.	_	Test Condition
Voltage at all pins to GND	V_{P}	0	-	5	V	-
Operating temperature range	T _{OP}	-40	-	+85	°C	-
Storage temperature range	T _{STG}	-65	-	+150	°C	-
Summed up input power for all pins	$P_{\rm in}$	-	-	60	mW	<i>T</i> _S < 70 °C
Electrostatic Discharge According to IEC61	000-4-2		L		-	
Contact discharge at internal pin C1 to any other pin	V _{ESD}	-2	-	2	kV	-
Contact discharge at external pins A1, A2, A3, B3, C3 to GND	V _{ESD}	-15	-	15	kV	-



Table 2 Electrical Characteristics¹⁾

Parameter	Symbol	Values			Unit	Note /
		Min.	Тур.	Max.		Test Condition
Resistors R_1 , R_2	<i>R</i> _{1,2}	1575	1750	1925	Ω	_
Resistor R ₃	R ₃	80	100	120	kΩ	_
Leakage current of ESD protection diodes	IR	-	1	100	nA	<i>V</i> = 3 V
		-	2	200	nA	V = 5 V
Breakdown voltage of ESD diodes ²⁾	V _(BR)	-	18.5	-	V	I _(BR) = 1 mA
	(2.1)		-12.5			$I_{(BR)}$ = -1 mA
Line capacitance						
A1, A2, A3, B3, C3 ³⁾	CT	8	10	12	pF	V = 0 V
	1	1	1	-1	1	1

1) at *T*_A = 25 °C

2) after snap-back

3) Capacitance measured from designated pin to GND. Pin C1 connected to GND.

Package Outlines

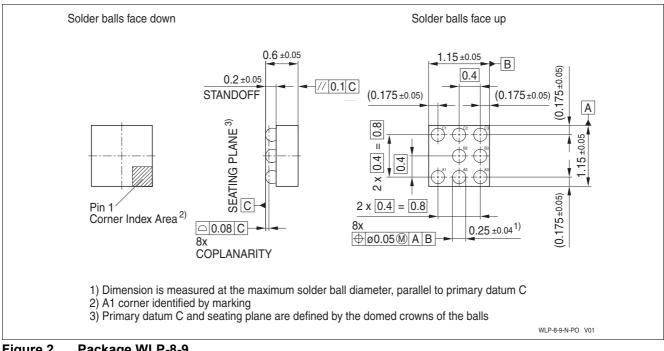
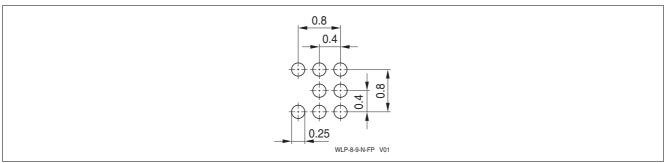


Figure 2 Package WLP-8-9



Footprint





Таре

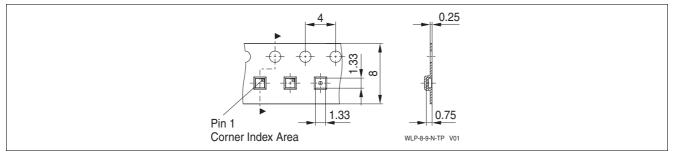


Figure 4 Tape for WLP-8-9

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